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Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



Description

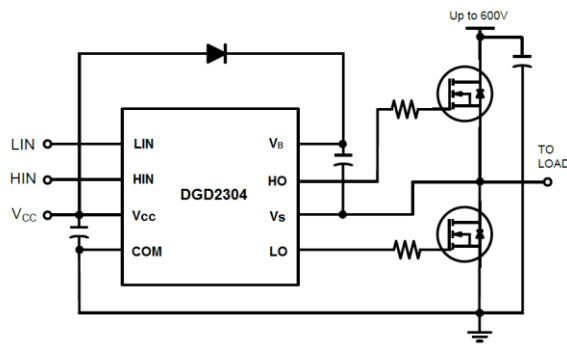
The DGD2304 is a high voltage / high speed gate driver capable of driving N-channel MOSFETs and IGBTs in a half bridge configuration. High voltage processing techniques enable the DGD2304's high side to switch to 600V in a bootstrap operation.

The DGD2304 logic inputs are compatible with standard TTL and CMOS levels (down to 3.3V) to interface easily with controlling devices. The driver outputs feature high pulse current buffers designed for minimum driver cross conduction. An internal deadtime of 100ns protects high-voltage MOSFETs from shoot-through.

The DGD2304 is offered in the SO-8 (Type TH) package and operates over an extended -40°C to +125°C temperature range.

Applications

- DC-DC Converters
- DC-AC Inverters
- AC-DC Power Supplies
- Motor Controls
- Class D Power Amplifiers



Typical Configuration

Features

- Floating High-Side Driver In Bootstrap Operation to 600V
- Drives Two N-channel MOSFETs or IGBTs in a Half Bridge Configuration
- 290mA Source/600mA Sink Output Current Capability
- Outputs Tolerant to Negative Transients
- Internal Logic and Dead Time (100ns) to Protect MOSFETs
- Logic Input (HIN and LIN) 3.3V Capability
- Schmitt Triggered Logic Inputs with Internal Pull Down
- Undervoltage Lockout for High and Low Side Drivers
- Extended Temperature Range: -40°C to +125°C
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

Mechanical Data

- Case: SO-8 (Type TH)
- Case Material: Molded Plastic. "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Terminals: Finish – Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208
- Weight: 0.075 grams (Approximate)



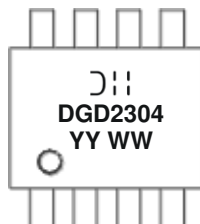
SO-8 (Type TH)
Top View

Ordering Information (Note 4)

Product	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
DGD2304S8-13	DGD2304	13	12	2,500

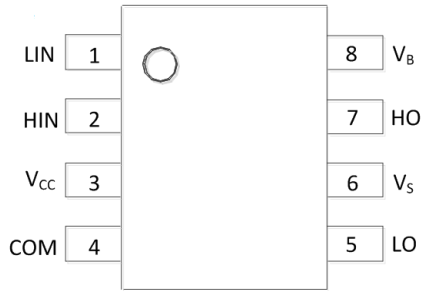
- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information



- = Manufacturer's marking
- DGD2304 = Product Type Marking Code
- YY = Year (ex: 16 = 2016)
- WW = Week (01 to 53)

Pin Diagrams

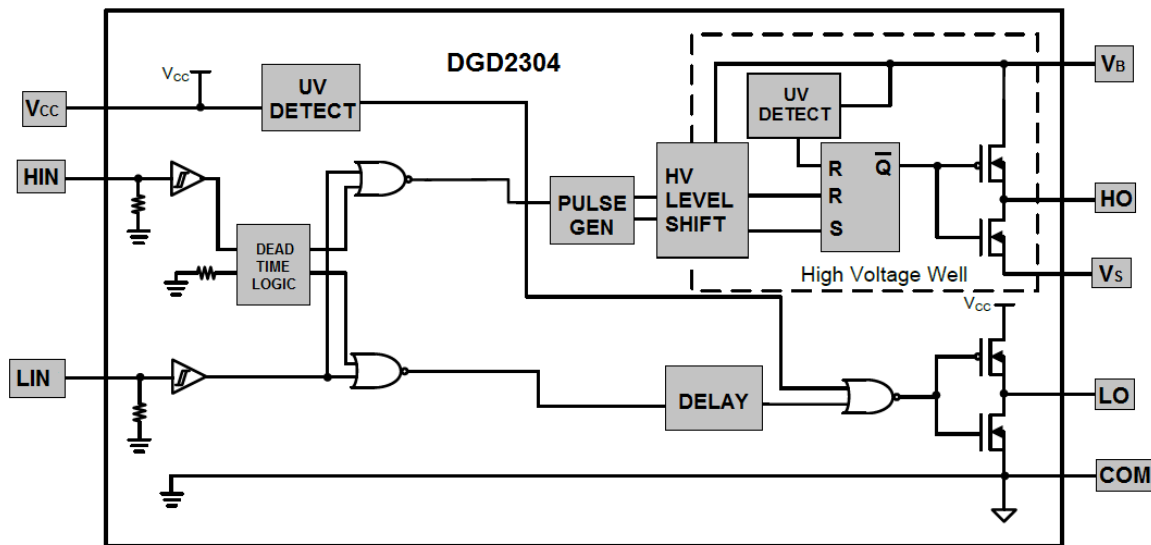


Top View: SO-8 (Type TH)

Pin Descriptions

Pin Number	Pin Name	Function
1	LIN	Logic input for Low-Side Gate Driver Output in Phase with LO
2	HIN	Logic Input for High-Side Gate Driver Output in Phase with HO
3	V _{CC}	Low Side and Logic Fixed Supply
4	COM	Low-Side and Logic Return
5	LO	Low-Side Gate Drive Output
6	V _S	High-Side Floating Supply Return
7	HO	High-Side Gate Drive Output
8	V _B	High-Side Floating Supply

Functional Block Diagram



Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
High-Side Floating Supply Voltage	V _B	-0.3 to +624	V
High-Side Floating Supply Offset Voltage	V _S	V _B -24 to V _B +0.3	V
High-Side Floating Output Voltage	V _{HO}	V _S -0.3 to V _B +0.3	V
Offset Supply Voltage Transient	dV _S / dt	50	V/ns
Low-Side and Logic Fixed Supply Voltage	V _{CC}	-0.3 to +24	V
Low-Side Output Voltage	V _{LO}	-0.3 to V _{CC} +0.3	V
Logic Input Voltage (HIN and LIN)	V _{IN}	V _{SS} -0.3 to V _{CC} +0.3	V

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation Linear derating factor (Note 5)	P _D	1.25	W
Thermal Resistance, Junction to Ambient (Note 5)	R _{θJA}	55	°C/W
Operating Temperature	T _J	+150	°C
Lead Temperature (Soldering, 10s)	T _L	+300	
Storage Temperature Range	T _{STG}	-55 to +150	

Note: 5. When mounted on a standard JEDEC 2-layer FR-4 board.

Recommended Operating Conditions

Parameter	Symbol	Min	Max	Unit
High Side Floating Supply Absolute Voltage	V _B	V _S + 10	V _S + 20	V
High Side Floating Supply Offset Voltage	V _S	(Note 6)	600	V
High Side Floating Output Voltage	V _{HO}	V _S	V _B	V
Low Side and Logic Fixed Supply Voltage	V _{CC}	10	20	V
Low Side Output Voltage	V _{LO}	0	V _{CC}	V
Logic Input Voltage	V _{IN}	0	5	V
Ambient Temperature	T _A	-40	+125	°C

Note: 6. Logic operation for V_S of -5V to +600V. Logic state held for V_S of -5V to -V_Bs.

DC Electrical Characteristics (V_{BIAS} (V_{CC} , V_{BS}) = 15V, @ T_A = +25°C, unless otherwise specified.) (Note 7)

Parameter	Symbol	Min	Typ	Max	Unit	Conditions
Logic "1" Input Voltage	V_{IH}	2.3	–	–	V	$V_{CC} = 10V$ to 20V
Logic "0" Input Voltage	V_{IL}	–	–	0.7	V	$V_{CC} = 10V$ to 20V
High Level Output Voltage, $V_{BIAS} - V_O$	V_{OH}	–	0.05	0.2	V	$I_O = 2mA$
Low Level Output Voltage, V_O	V_{OL}	–	0.02	0.1	V	$I_O = 2mA$
Offset Supply Leakage Current	I_{LK}	–	–	50	μA	$V_B = V_S = 600V$
Quiescent V_{BS} Supply Current	I_{BSQ}	20	60	150	μA	$V_{IN} = 0V$ or 5V
Quiescent V_{CC} Supply Current	I_{CCQ}	50	260	400	μA	$V_{IN} = 0V$ or 5V
Logic "1" Input Bias Current	I_{IN+}	–	5.0	40	μA	$V_{IN} = 5V$
Logic "0" Input Bias Current	I_{IN-}	–	1.0	5.0	μA	$V_{IN} = 0V$
V_{BS} Supply Under-Voltage Positive Going Threshold	V_{BSUV+}	7.7	8.7	9.7	V	–
V_{BS} Supply Under-Voltage Negative Going Threshold	V_{BSUV-}	7.0	8.0	9.0	V	–
V_{CC} Supply Under-Voltage Positive Going Threshold	V_{CCUV+}	7.7	8.7	9.7	V	–
V_{CC} Supply Under-Voltage Negative Going Threshold	V_{CCUV-}	7.0	8.0	9.0	V	–
Output High Short Circuit Pulsed Current	I_{O+}	60	290	–	mA	$V_O = 0V$, $PW \leq 10\mu s$
Output Low Short Circuit Pulsed Current	I_{O-}	130	600	–	mA	$V_O = 15V$, $PW \leq 10\mu s$

Note: 7. The V_{IN} and I_{IN} parameters are referenced to COM and are applicable to the two logic pins: HIN and LIN. The V_O and I_O parameters are referenced to COM and are applicable to the respective output pins: HO and LO.

AC Electrical Characteristics (V_{BIAS} (V_{CC} , V_{BS}) = 15V, $C_L = 1000pF$, @ T_A = +25°C, unless otherwise specified.)

Parameter	Symbol	Min	Typ	Max	Unit	Conditions
Turn-on Propagation Delay	t_{ON}	–	95	210	ns	$V_S = 0V$
Turn-off Propagation Delay	t_{OFF}	–	100	210	ns	$V_S = 0V$ or 600V
Delay Matching, HO & LO Turn-On / Turn-Off	t_{DMON}	–	–	50	ns	–
Turn-on Rise Time	t_R	–	70	120	ns	–
Turn-off Fall Time	t_F	–	35	60	ns	–
Deadtime: $t_{DT LO-HO}$ & $t_{DT HO-LO}$	t_{DT}	80	100	190	ns	–

Timing Waveforms

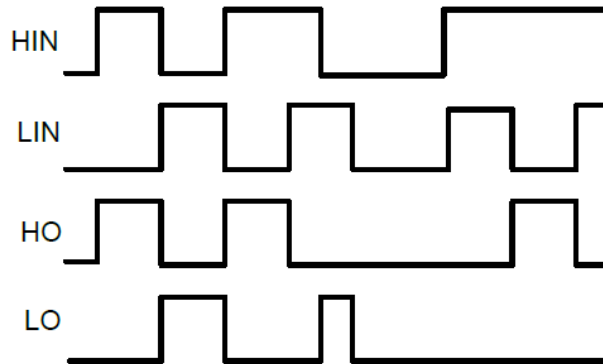


Figure 1. Input / Output Timing Diagram

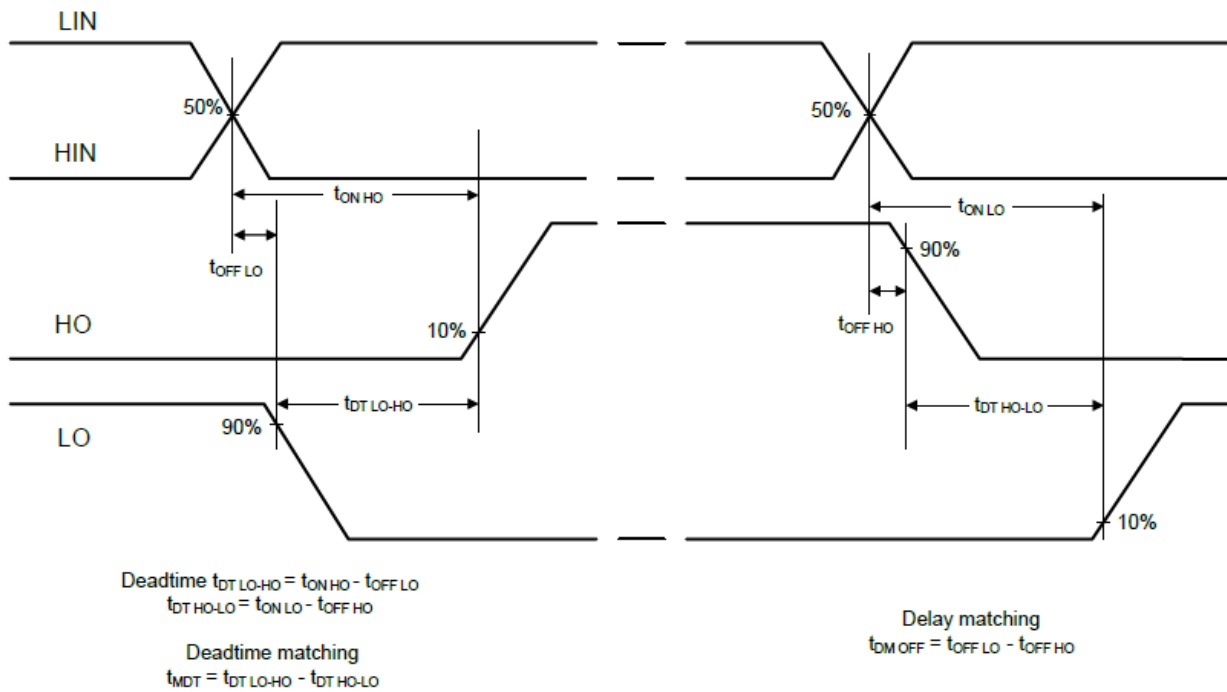


Figure 2. Switching Time Waveform Definition

Typical Performance Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

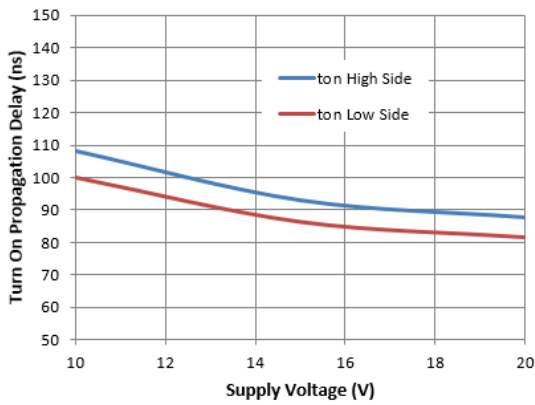


Figure 3. Turn-on Propagation Delay vs. Supply Voltage

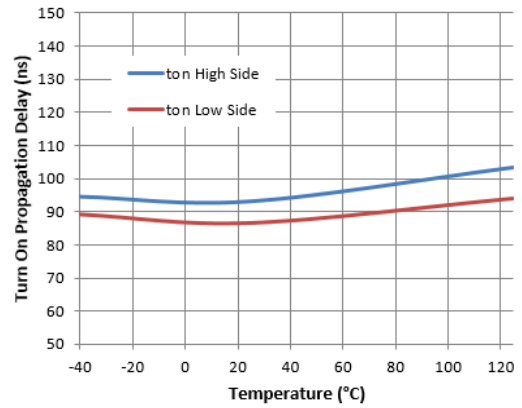


Figure 4. Turn-on Propagation Delay vs. Temperature

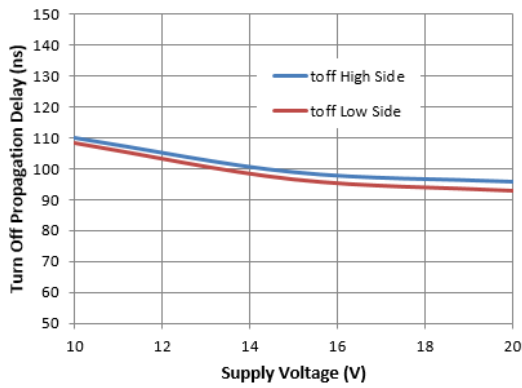


Figure 5. Turn-off Propagation Delay vs. Supply Voltage

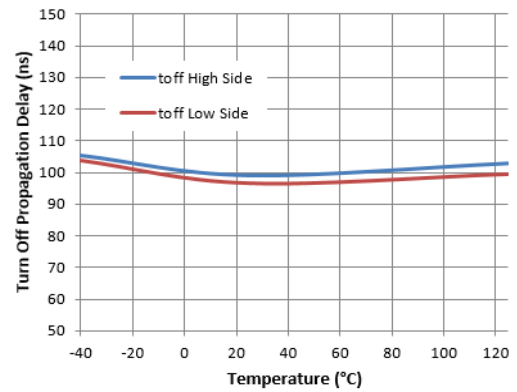


Figure 6. Turn-off Propagation Delay vs. Temperature

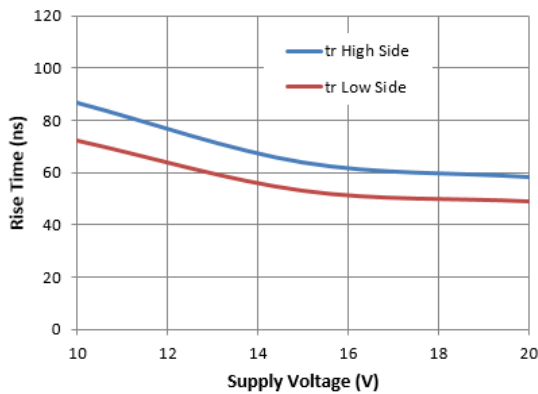


Figure 7. Rise Time vs. Supply Voltage

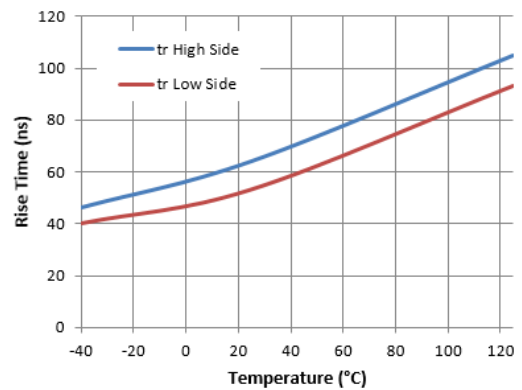


Figure 8. Rise Time vs. Temperature

Typical Performance Characteristics (Cont.)

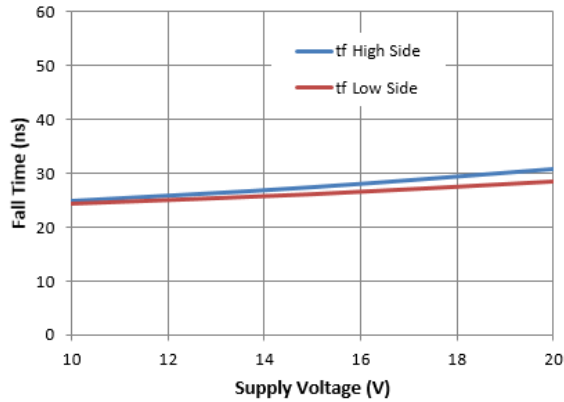


Figure 9. Fall Time vs. Supply Voltage

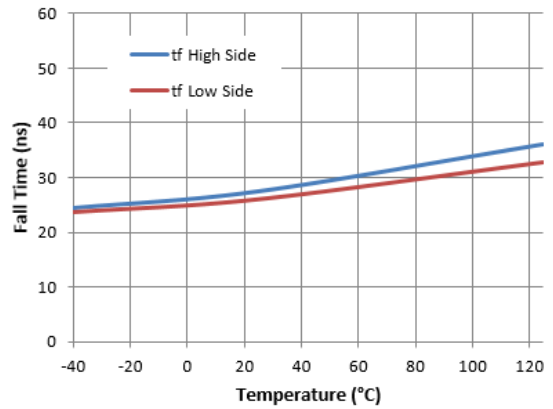


Figure 10. Fall Time vs. Temperature

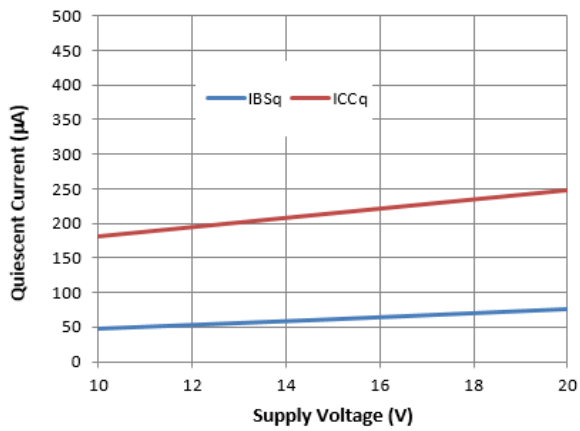


Figure 11. Quiescent Current vs. Supply Voltage

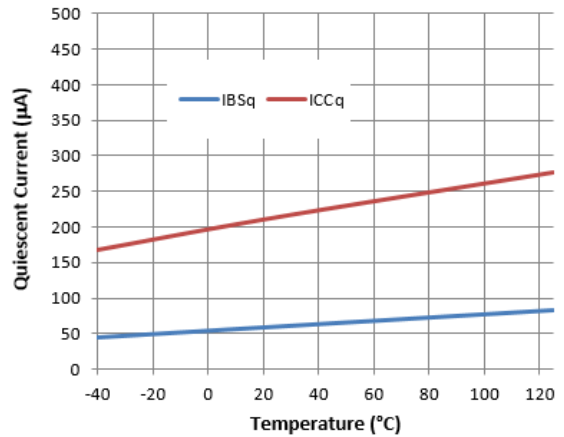


Figure 12. Quiescent Current vs. Temperature

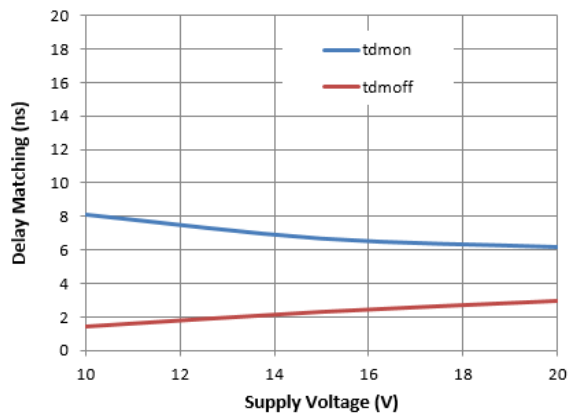


Figure 13. Delay Matching vs. Supply Voltage

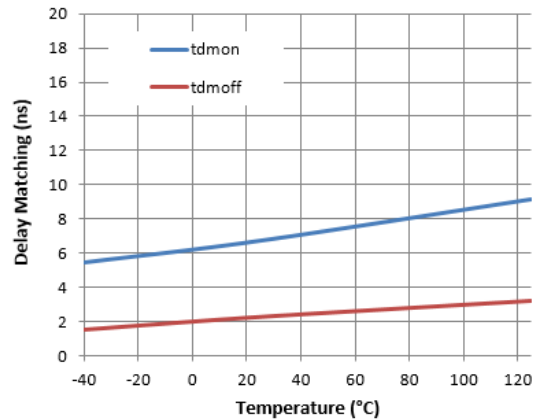


Figure 14. Delay Matching vs. Temperature

Typical Performance Characteristics (Cont.)

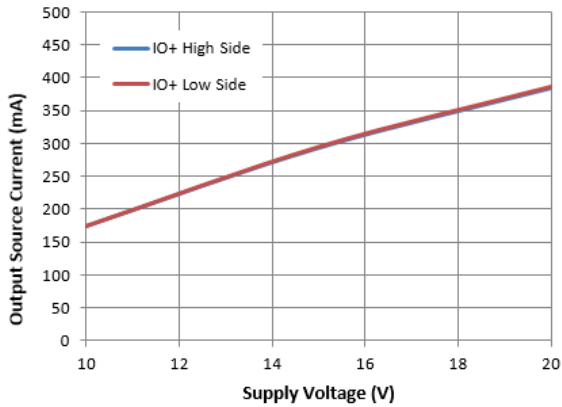


Figure 15. Output Source Current vs. Supply Voltage

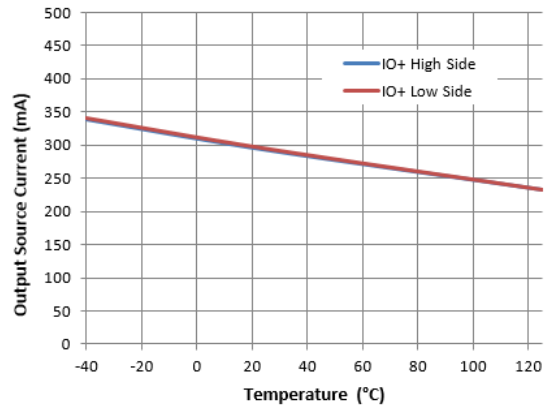


Figure 16. Output Source Current vs. Temperature

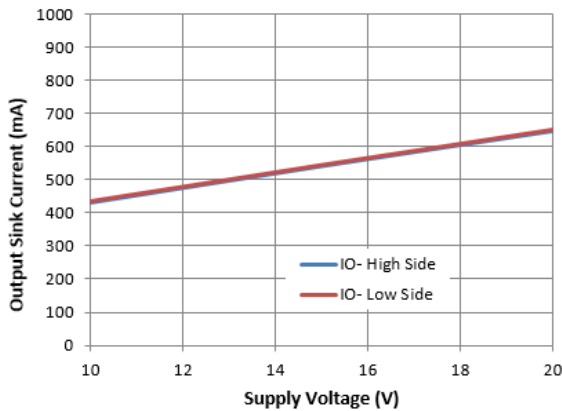


Figure 17. Output Sink Current vs. Supply Voltage

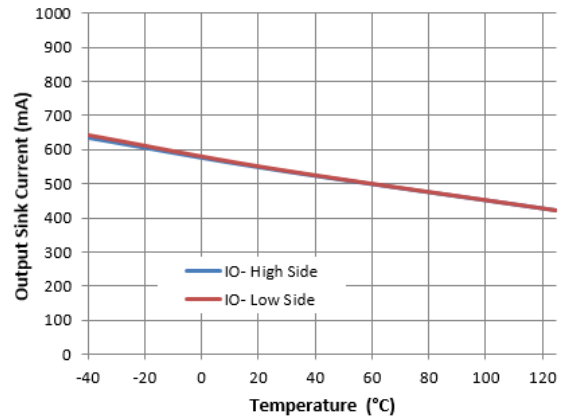


Figure 18. Output Sink Current vs. Temperature

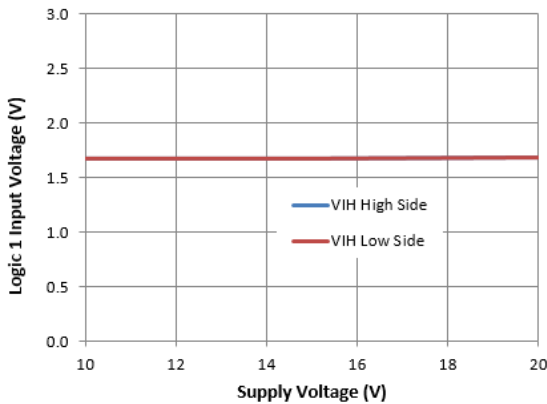


Figure 19. Logic 1 Input Voltage vs. Supply Voltage

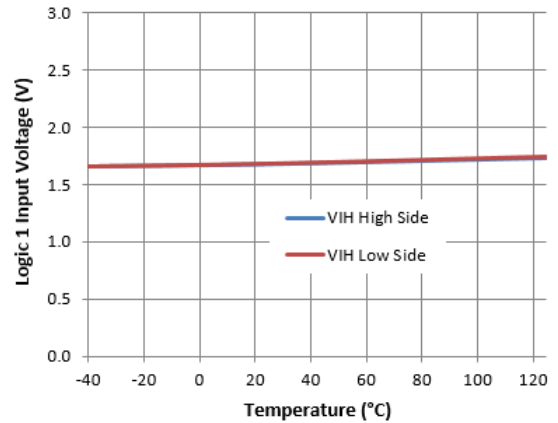


Figure 20. Logic 1 Input Voltage vs. Temperature

Typical Performance Characteristics (Cont.)

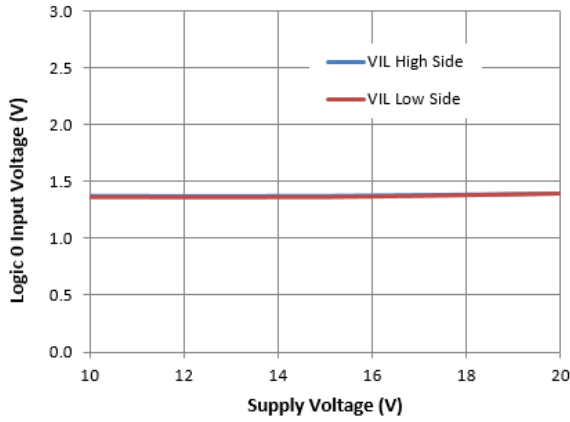


Figure 21. Logic 0 Input Voltage vs. Supply Voltage

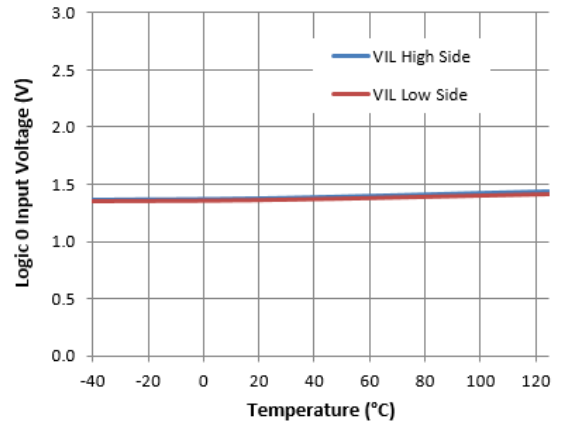


Figure 22. Logic 0 Input Voltage vs. Temperature

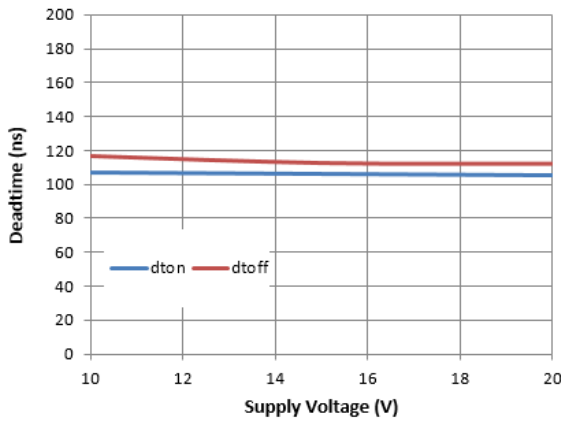


Figure 23. Deadtime vs. Supply Voltage

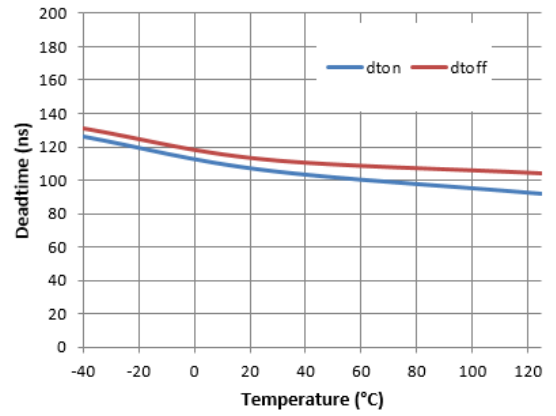


Figure 24. Deadtime vs. Temperature

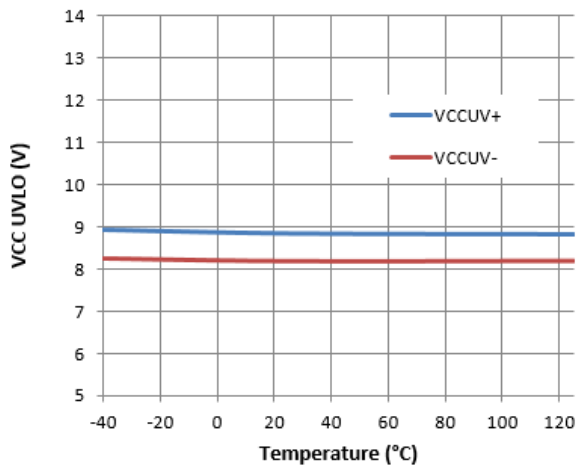


Figure 25. VCC UVLO vs. Temperature

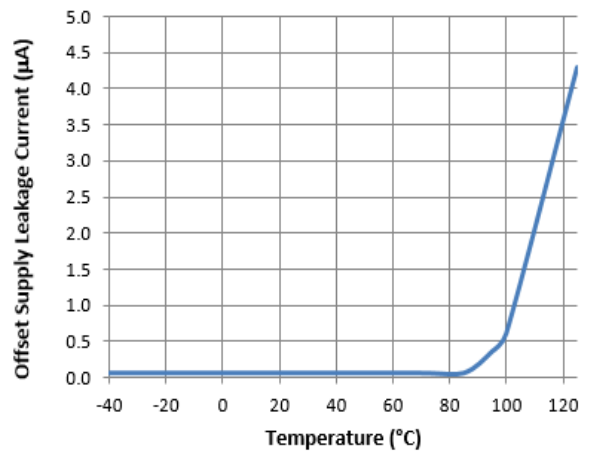
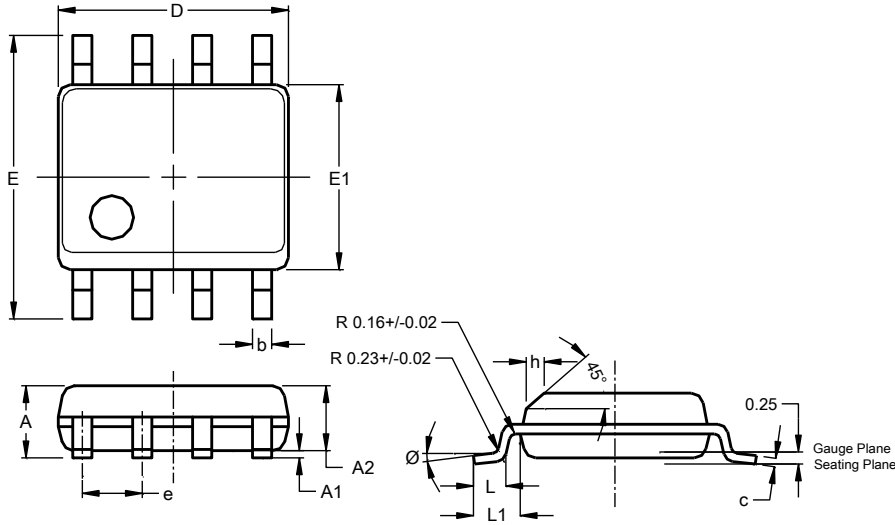


Figure 26. Offset Supply Leakage Current vs. Temperature

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SO-8 (Type TH)

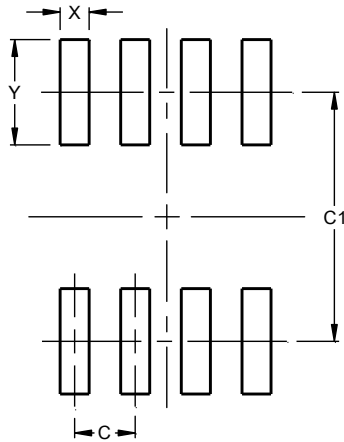


SO-8 (Type TH)			
Dim	Min	Max	Typ
A	1.35	1.75	--
A1	0.10	0.25	--
A2	--	--	1.45
b	0.35	0.51	--
c	0.190	0.248	--
D	4.80	5.00	4.90
E	5.80	6.20	6.00
E1	3.80	4.00	3.90
e	--	--	1.27
h	0.25	0.50	--
L	0.41	1.27	--
L1	--	--	1.04
Ø	0°	8°	--
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SO-8 (Type TH)



Dimensions	Value (in mm)
C	1.27
C1	5.20
X	0.60
Y	2.20

Note : For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.

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